



TSK UF 200AL Prober

HARDWARE COMPONENTS:

- Main Control System Based on VME Bus
- Hard Disk Drive
- 3 ½" Floppy Disk Drive
- Head Stage (Standard ITP)
- 1st Cassette Loader for 25 Wafers (5 to 8 inch wafers)
- Manual Wafer Inspection Transfer Unit
- Dual Robotic Wafer Transport Arms
- Pre-Alignment Stage Unit
- Capacitive Non-Contact Displacement Sensor
- Advanced Wafer Alignment Unit
- Dual (X & Y) Moiré Scales
- High Rigidity Z Stage
- Color LCD Panel with Touch Panel Switches
- Alarm Lamp Pole

SOFTWARE FUNCTIONS

- Automatic Probe to Pad Alignment
- Automatic Needle Height Alignment
- GPIB Interface w/4m Cable
- Tester Communications (TTL) Port
- Multi-Site Parallel Probing for 2 sites
- Sample Die Probing
- Edge Die Marking
- Real Time Color Wafer Map
- 80 Column External Printer interface (Printer Not Included)

MISCELLANEOUS

- Operations & Maintenance Manuals
- Standard Accessories
 - Set-up Disk
 - Data Diskette
 - Needle Cleaning Standard Pad Type, w/50mm Dia. (1)
 - Needle Cleaning, Brush Type, w/15mm Sq. Brush (1)
 - Vertical Probe Cleaning Soft
 - Bump Height Setting for Bump-Pad Wafers
 - Off-Site Marking Option
 - 4GT Xandex Inker (1)
 - Fail Mark (Ink Dot) Inspection Option
 - Probe Mark Inspection Option
 - Std. Hot Check Option (+50°C ~+150°C), 8", Kanizen Plated + Cont.

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